Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L3	0	("20040166603").PN.	USPAT; USOCR	OR	OFF	2005/09/22 12:59
L4	1	("20040166603").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2005/09/22 12:59
L5	12945	(@ad<"20030226") and (actuator or acuators or witch or switches or mems or micro or sensor) and ((encapsulant or encapsulate or mold or epoxy) with (aperture or hole or trench or cavity or via))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/22 13:31
L6	4830	L5 and (remove or etch or milling)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/22 13:31
<b>L7</b>	238	L6 and "438"/\$.ccls.	US-PGPUB; USPAT;	OR	OFF	2005/09/22 13:35
			USOCR;	.2	3 4 -	
			EPO; JPO; DERWENT;			
	<i>i</i> .		IBM_TDB	. ' ' ' ' ' ' ' ' ' ' ' ' ' ' ' ' ' ' '		
L8	375	L5 and "438"/\$.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/22 13:35
L9	0	-L7 not L8	US-PGPUB; USPAT;	OR	OFF	2005/09/22 13:35
		in the second of	USOCR; EPO; JPO;	×1	i de la companya de l	
			DERWENT;	· .	ta ta	
	453	1.5 - 1.4 (1057) (4.5)	IBM_TDB	OD	90.8	2005/00/22 12:26
L10	457	L6 and "257"/\$.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/22 13:36
L11	8942	(@ad<"20030226") and (mems or micro or sensor) and ((encapsulant or encapsulate or mold or epoxy) with (aperture or hole or trench or cavity or via))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF 2	2005/09/22 13:36

L12	778	L11 and "257"/\$.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/22 13:36
L13	62	L10 not L12	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/22 13:36
S1	6024	(@ad<"20030226") and (mems or sensor) and ((encapsulant or encapsulate or mold or epoxy) with (aperture or hole or trench or cavity or via))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/22 11:11
<b>S2</b>	2098	S1 and (chip or die)	US-PGPUB; USPAT;	OR	OFF	2005/09/22 11:06
	7	19 19 19 19 19 19 19 19 19 19 19 19 19 1	USOCR; EPO; JPO;	A	· • • • • • • •	
			DERWENT; IBM_TDB		- ax 1	g. Dec
<b>S3</b>	1390	S2 and (cure or curing or heat or harden)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/22 11:07
<b>S4</b>	8942	(@ad<"20030226") and (mems or micro or sensor) and ((encapsulant	US-PGPUB; USPAT;	OR	OFF	2005/09/22 11:46
* 3.8	The state of the s	or encapsulate or mold or epoxy) with (aperture or hole or trench or	USOCR; EPO; JPO;			24
:20		cavity or via))	DERWENT; IBM_TDB			
S5	778	S4 and "257"/\$.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/22 11:14
S6	6	S4 and "257"/790.ccls.	US-PGPUB; USPAT;	OR	OFF	2005/09/22 11:14
7.4.± 2		the second that the	USOCR; EPO; JPO;	, s		E ×
	, () 		DERWENT; IBM_TDB			\$5°

S7	51	(@ad<"20030226") and (mems or micro or sensor) and 257/790.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/22 11:35
S8	59	(@ad<"20030226") and (mems or micro or sensor or actuator or sensors or actuators or switches or sitch) and 257/790.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/22 11:45
S9	8	S8 not S7	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/22 11:36
S10	12945	(@ad<"20030226") and (actuator or acuators or witch or switches or mems or micro or sensor) and ((encapsulant or encapsulate or mold or epoxy) with (aperture or hole or trench or cavity or via))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/22 13:31
S11	375	S10 and "438"/\$.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/22 13:34